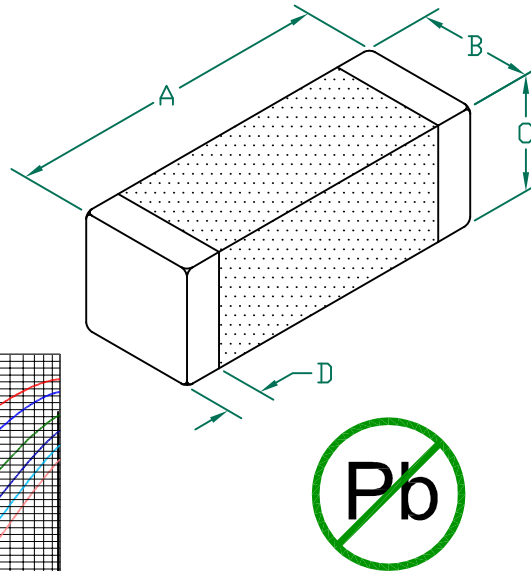


HI1806T600R-10

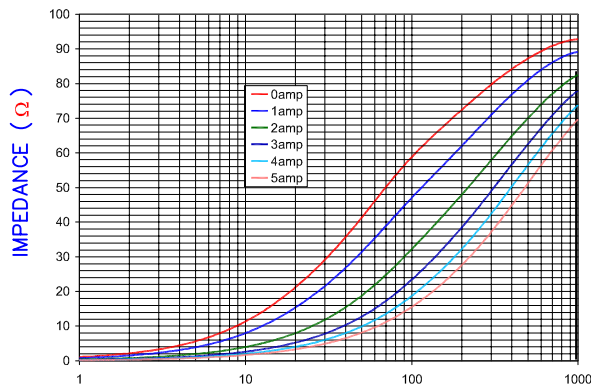
**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

A	4.50 [.177]	+ 0.25 [.010]
B	1.60 [.063]	+ 0.25 [.010]
C	1.60 [.063]	+ 0.25 [.010]
D	0.51 [.020]	+ 0.25 [.010]

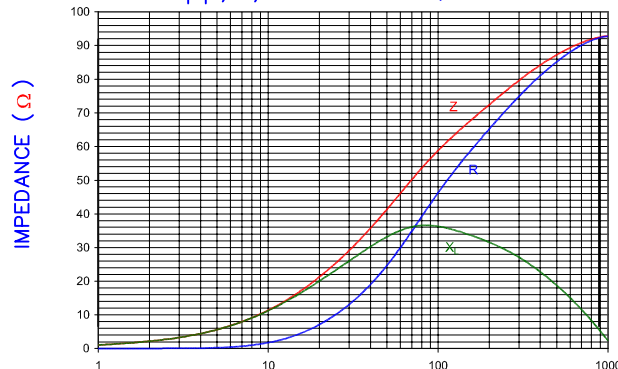


Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

— Z — R — X_L

AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3124

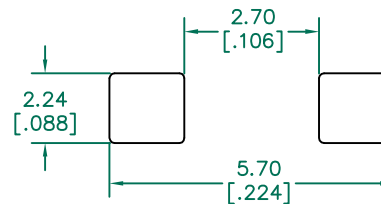
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	60	
Minimum	45	
Maximum	75	0.010 6000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

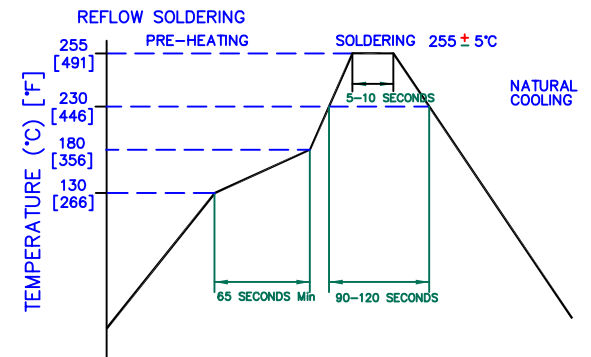
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 2,000 PCS/REEL. EMBOSSED PLASTIC TAPE.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
H	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU				
G	CHANGE SOLDERING TEMPERATURE FROM 250	07/08/10	JUN				
F	CHANGE REEL QTY FROM 3K TO 2K	11/06/08	JRK				
E	UPDATE COMPANY LOGO	06/19/08	JRK				
D	UPDATE COMPANY LOGO ADD ROHS SYMBOL	01/18/08	JRK				
C	ADD DC BIAS CURVE, CORRECT LANDPATTERN	03/07/03	JRK	PROJECT/PART NUMBER: HI1806T600R-10			
B	REMOVE NOTE 3	09/14/01	JRK	DATE: 01/12/01			
A	ORIGINAL DRAFT	01/12/01	BAC	SCALE: NTS			
REV	DESCRIPTION	DATE	INT	TOOL # -			
				SHEET: 2 of 2			